



**Product Data Sheet and
General Processing Conditions**

**RTP 4899 X 146514
Polyvinylchloride (PVC)
Electrically Conductive
Extrusion
Preliminary**

PROPERTIES & AVERAGE VALUES OF INJECTION MOLDED SPECIMENS

PERMANENCE		STANDARD
Density	1.33 g/cm ³	DIN 53479
MECHANICAL		
Tensile Stress		
At Break	> 12 MPa	ISO 527-2/1A
Tensile Strain		
At Break	> 50 %	ISO 527-2/1A
Shore Hardness	95 A	DIN 53505
ELECTRICAL		
Surface Resistance (23 °C, 50% RH)		
Flat film, 800 µm	< 10 ² ohm	IEC 93

DATA NOTES

Data herein is typical and not to be construed as specifications.
Unless otherwise specified, all data listed is for natural or black colored materials. Pigments can affect properties.

GENERAL PROCESSING GUIDELINES

Melt Temperature	165-190 °C
Die Temperature	195 °C
Drying	4-6 hr @ 60 °C

PROCESSING NOTES

None.

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This information is intended to be used only as a guideline for designers and processors of modified thermoplastics for injection molding. Because injection mold design and processing is complex, a set solution will not solve all problems. Observation on a "trial and error" basis may be required to achieve desired results.

Data are obtained from specimens molded under carefully controlled conditions from representative samples of the compound described herein. Properties may be materially affected by molding techniques applied and by the size and shape of the item molded. No assurance can be implied that all molded articles will have the same properties as those listed.

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